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Industriell processtyrning – Fältbuss –

Del 2: Specifikation av det fysiska skiktet och definition av dess tjänster

Industrial communication networks –

Fieldbus specifications –

Part 2: Physical layer specification and service definition

Som svensk standard gäller europastandarden EN 61158-2:2014. Den svenska standarden innehåller den officiella engelska språkversionen av EN 61158-2:2014.

Nationellt förord

Europastandarden EN 61158-2:2014

består av:

- **europastandardens ikraftsättningsdokument**, utarbetat inom CENELEC
- **IEC 61158-2, Sixth edition, 2014 - Industrial communication networks - Fieldbus specifications - Part 2: Physical layer specification and service definition**

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English Version

**Industrial communication networks - Fieldbus specifications -
Part 2: Physical layer specification and service definition
(IEC 61158-2:2014)**

Réseaux de communication industriels - Spécifications des
bus de terrain - Partie 2: Spécification et définition des
services de la couche physique
(CEI 61158-2:2014)

Industrielle Kommunikationsnetze - Feldbusse - Teil 2:
Spezifikation und Dienstfestlegungen des Physical Layer
(Bitübertragungsschicht)
(IEC 61158-2:2014)

This European Standard was approved by CENELEC on 2014-08-21. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 65C/758A/FDIS, future edition 6 of IEC 61158-2, prepared by SC 65C "Industrial networks" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61158-2:2014.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2015-05-21
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2017-08-21

This document supersedes EN 61158-2:2010.

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Endorsement notice

The text of the International Standard IEC 61158-2:2014 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60079-0	NOTE	Harmonized as EN 60079-0.
IEC 60875-1	NOTE	Harmonized as EN 60875-1.
IEC 60947-5-2	NOTE	Harmonized as EN 60947-5-2.
IEC 61158	NOTE	Harmonized as EN 61158 series.
IEC 61158-1:2014	NOTE	Harmonized as EN 61158-1:2014 (not modified).
IEC 61158-4-1:2014	NOTE	Harmonized as EN 61158-4-1 ¹⁾ (not modified).
IEC 61158-4-4:2014	NOTE	Harmonized as EN 61158-4-4 ¹⁾ (not modified).
IEC 61158-4-7:2007	NOTE	Harmonized as EN 61158-4-7:2008 (not modified).
IEC 61158-4-8:2007	NOTE	Harmonized as EN 61158-4-8:2008 (not modified).
IEC 61158-4-12:2014	NOTE	Harmonized as EN 61158-4-12 ¹⁾ (not modified).

1) To be published

IEC 61158-4-16:2007	NOTE	Harmonized as EN 61158-4-16:2008 (not modified).
IEC 61158-4-18:2010	NOTE	Harmonized as EN 61158-4-18:2012 (not modified).
IEC 61158-4-20:2014	NOTE	Harmonized as EN 61158-4-20 ¹⁾ (not modified).
IEC 61158-4-24:2014	NOTE	Harmonized as EN 61158-4-24 ¹⁾ (not modified).
IEC 61300-3-4	NOTE	Harmonized as EN 61300-3-4.
IEC/TR 61491	NOTE	Harmonized as CLC/TR 61491.
IEC 61596	NOTE	Harmonized as EN 61596.
IEC 61784-1	NOTE	Harmonized as EN 61784-1.
IEC 61784-2	NOTE	Harmonized as EN 61784-2.

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60050	series	International Electrotechnical Vocabulary (IEV)	-	-
IEC 60079-11	-	Explosive atmospheres - Part 11: Equipment protection by intrinsic safety "i"	EN 60079-11	-
IEC 60079-14 -	2007 -	Explosive atmospheres - Part 14: Electrical installations design, selection and erection	EN 60079-14 + AC	2008 2011
IEC 60079-25	-	Explosive atmospheres - Part 25: Intrinsically safe electrical systems	EN 60079-25	-
IEC 60169-17	-	Radio-frequency connectors Part 17: R.F. coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with screw coupling - Characteristic impedance 50 ohms (Type TNC)	-	-
IEC 60189-1	2007	Low-frequency cables and wires with PVC insulation and PVC sheath - Part 1: General test and measuring methods	-	-
IEC 60255-22-1	1988	Electrical relays - Part 22: Electrical disturbance tests for measuring relays and protection equipment - Section 1: 1 MHz burst disturbance tests	-	-
IEC 60364-4-41	-	Low-voltage electrical installations - Part 4-41: Protection for safety - Protection against electric shock	HD 60364-4-41	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60364-5-54	-	Low-voltage electrical installations - Part 5-54: Selection and erection of electrical equipment - Earthing arrangements and protective conductors	HD 60364-5-54	-
IEC 60529	-	Degrees of protection provided by enclosures (IP Code)	EN 60529	-
IEC 60603-7-4	-	Connectors for electronic equipment - Part 7-4: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 250 MHz	EN 60603-7-4	-
IEC 60754-2	-	Test on gases evolved during combustion of materials from cables - Part 2: Determination of acidity (by pH measurement) and conductivity	EN 60754-2	-
IEC 60793	series	Optical fibres	EN 60793	series
IEC 60793-2-30	2012	Optical fibres - Part 2-30: Product specifications - Sectional specification for category A3 multimode fibres	EN 60793-2-30	2013
IEC 60793-2-40	2009	Optical fibres - Part 2-40: Product specifications - Sectional specification for category A4 multimode fibres	EN 60793-2-40	2011
IEC 60794-1-2	2003	Optical fibre cables - Part 1-2: Generic specification - Basic optical cable test procedures	EN 60794-1-2	2003
IEC 60807-3	-	Rectangular connectors for frequencies below 3 MHz - Part 3: Detail specification for a range of connectors with trapezoidal shaped metal shells and round contacts - Removable crimp types with closed crimp barrels, rear insertion/rear extraction	-	-
IEC 60811-403	-	Electric and optical fibre cables - Test methods for non-metallic materials - Part 403: Miscellaneous tests - Ozone resistance tests on cross-linked compounds	EN 60811-403	-
IEC 60811-404	2012	Electric and optical fibre cables - Test methods for non-metallic materials - Part 404: Miscellaneous tests - Mineral oil immersion tests for sheaths	EN 60811-404	2012
IEC 61000-4-2	-	Electromagnetic compatibility (EMC) - Part 4-2: Testing and measurement techniques - Electrostatic discharge immunity test	EN 61000-4-2	-
IEC 61000-4-3	-	Electromagnetic compatibility (EMC) - Part 4-3: Testing and measurement techniques - Radiated, radio-frequency, electromagnetic field immunity test	EN 61000-4-3	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61000-4-4	-	Electromagnetic compatibility (EMC) - Part 4-4: Testing and measurement techniques - Electrical fast transient/burst immunity test	EN 61000-4-4	-
IEC 61131-2	2007	Programmable controllers - Part 2: Equipment requirements and tests	EN 61131-2	2007
IEC 61156-1	2007	Multicore and symmetrical pair/quad cables for digital communications - Part 1: Generic specification	-	-
IEC 61158-3-20	2014	Industrial communication networks - Fieldbus specifications - Part 3-20: Data-link layer service definition - Type 20 elements	EN 61158-3-20	2014
IEC 61158-4-2	2014	Industrial communication networks - Fieldbus specifications - Part 4-2: Data-link layer protocol specification - Type 2 elements	EN 61158-4-2	2)
IEC 61158-4-3	2014	Industrial communication networks - Fieldbus specifications - Part 4-3: Data-link layer protocol specification - Type 3 elements	EN 61158-4-3	2)
IEC 61169-8	2007	Radio-frequency connectors - Part 8: Sectional specification - RF coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with bayonet lock - Characteristics impedance 50 ohms (type BNC)	EN 61169-8	2007
IEC 61210 (mod)	2010	Connecting devices - Flat quick-connect terminations for electrical copper conductors - Safety requirements	EN 61210	2010
IEC 61754-2	-	Fibre optic connector interfaces - Part 2: Type BFOC/2,5 connector family	EN 61754-2	-
IEC 61754-13	-	Fibre optic connector interfaces - Part 13: Type FC-PC connector	EN 61754-13	-
IEC 61754-22	-	Fibre optic connector interfaces - Part 22: Type F-SMA connector family	EN 61754-22	-
ISO/IEC 7498	series	Information technology - Open Systems Interconnection - Basic Reference Model	-	-
ISO/IEC 7498-1	1994	Information technology - Open Systems Interconnection - Basic Reference Model: The Basic Model	-	-
ISO/IEC 8482	-	Information technology - Telecommunications and information exchange between systems - Twisted pair multipoint interconnections	-	-

2) To be published.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
ISO/IEC 8802-3	-	Information technology - Telecommunications and information exchange between systems - Local and metropolitan area networks - Specific requirements - Part 3: Carrier sense multiple access with collision detection (CSMA/CD) access method and physical layer specifications	-	-
ISO/IEC 10731	1994	Information technology - Open Systems Interconnection - Basic Reference Model - Conventions for the definition of OSI services	-	-
ISO 4892-1	-	Plastics - Methods of exposure to laboratory light sources - Part 1: General guidance	EN ISO 4892-1	-
ISO 9314-1	-	Information Processing Systems - Fibre distributed data interface (FDDI) - Part 1: Token Ring physical layer protocol (PHY)	-	-
ANSI TIA/EIA-422-B	-	Electrical Characteristics of Balanced Voltage Digital Interface Circuits	-	-
ANSI TIA/EIA-485-A	-	Electrical Characteristics of Generators and Receivers for Use in Balanced Digital Multipoint Systems	-	-
ANSI TIA/EIA-644-A	-	Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits	-	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

INDUSTRIAL COMMUNICATION NETWORKS – FIELDBUS SPECIFICATIONS –

Part 2: Physical layer specification and service definition

FOREWORD

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NOTE Combinations of protocol types are specified in IEC 61784-1 and IEC 61784-2.

International Standard IEC 61158-2 has been prepared by subcommittee 65C: Industrial networks, of IEC technical committee 65: Industrial-process measurement, control and automation.

This sixth edition cancels and replaces the fifth edition published in 2010. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- new Type 20 specification in 3.12, 4.1.11, 4.2.11, 5.12, Clause 34 and Annex T;
- new Type 24 specification in 3.11, 4.2.10, 5.11, 6.9, 9.12, Clause 33 and Annex S;
- Clause 17 Type 1: Medium attachment unit: radio signaling deleted due to lack of support;
- RS232 media specification for Type 4 removed, because it is not in use any more.

The text of this standard is based on the following documents:

FDIS	Report on voting
65C/758A/FDIS	65C/775/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with ISO/IEC Directives, Part 2.

NOTE Slight variances from the directives have been allowed by the IEC Central Office to provide continuity of subclause numbering with prior editions.

The list of all the parts of the IEC 61158 series, published under the general title *Industrial communication networks – Fieldbus specifications*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

0 Introduction

0.1 General

This part of IEC 61158 is one of a series produced to facilitate the interconnection of automation system components. It is related to other standards in the set as defined by the “three-layer” fieldbus reference model described in IEC 61158-1.

0.2 Physical layer overview

The primary aim of this standard is to provide a set of rules for communication expressed in terms of the procedures to be carried out by peer Ph-entities at the time of communication.

The physical layer receives data units from the data-link Layer, encodes them, if necessary by adding communications framing information, and transmits the resulting physical signals to the transmission medium at one node. Signals are then received at one or more other node(s), decoded, if necessary by removing the communications framing information, before the data units are passed to the data-link Layer of the receiving device.

0.3 Document overview

This standard comprises physical layer specifications corresponding to many of the different DL-Layer protocol Types specified in IEC 61158 series.

NOTE 1 The protocol Type numbers used are consistent throughout the IEC 61158 series.

NOTE 2 Specifications for Types 1, 2, 3, 4, 8, 16, 18, 20 and 24 are included. Type 7 uses Type 1 specifications. The other Types do not use any of the specifications given in this standard.

NOTE 3 For ease of reference, Type numbers are given in clause names. This means that the specification given therein applies to this Type, but does not exclude its use for other Types.

NOTE 4 It is up to the user of this standard to select interoperating sets of provisions. Refer to IEC 61784-1 or IEC 61784-2 for standardized communication profiles based on the IEC 61158 series.

A general model of the physical layer is shown in Figure 1.

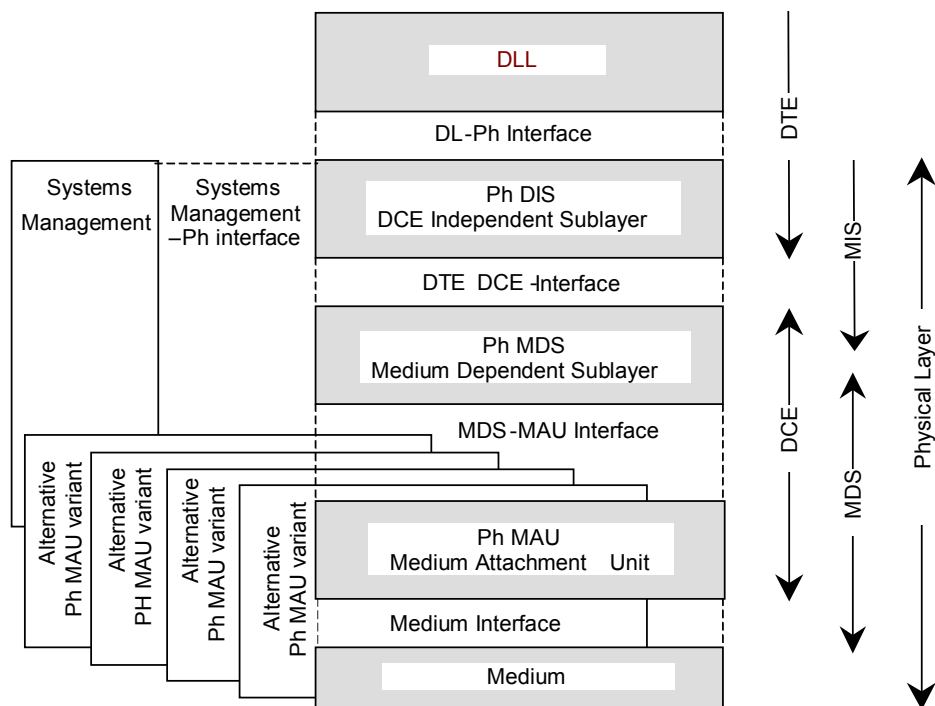


Figure 1 – General model of physical layer

NOTE 5 The protocol types use a subset of the structure elements.

NOTE 6 Since Type 8 uses a more complex DIS than the other types, it uses the term MIS to differentiate.

The common characteristics for all variants and types are as follows:

- digital data transmission;
- no separate clock transmission;
- either half-duplex communication (bi-directional but in only one direction at a time) or full-duplex communication.

0.4 Major physical layer variations specified in this standard

0.4.1 Type 1 media

0.4.1.1 Type 1: Wire media

For twisted-pair wire media, Type 1 specifies two modes of coupling and different signaling speeds as follows:

- a) voltage mode (parallel coupling), 150 Ω , data rates from 31,25 kbit/s to 25 Mbit/s;
- b) voltage mode (parallel coupling), 100 Ω , 31,25 kbit/s;
- c) current mode (serial coupling), 1,0 Mbit/s including two current options.

The voltage mode variations may be implemented with inductive coupling using transformers. This is not mandatory if the isolation requirements of this standard are met by other means.

The Type 1 twisted-pair (or untwisted-pair) wire medium physical layer provides the options:

- no power via the bus conductors; not intrinsically safe;
- power via the bus conductors; not intrinsically safe;
- no power via the bus conductors; intrinsically safe;
- power via the bus conductors; intrinsically safe.

0.4.1.2 Type 1: Optical media

The major variations of the Type 1 optic fiber media are as follows:

- dual fiber mode, data rates from 31,25 kbit/s to 25 Mbit/s;
- single fiber mode, 31,25 kbit/s.

0.4.2 Type 2: Coaxial wire and optical media

Type 2 specifies the following variants:

- coaxial copper wire medium, 5 Mbit/s;
- optical fiber medium, 5 Mbit/s;
- network access port (NAP), a point-to-point temporary attachment mechanism that can be used for programming, configuration, diagnostics or other purposes;
- repeater machine sublayers (RM, RRM) and redundant physical layers.

0.4.3 Type 3: Twisted-pair wire and optical media

Type 3 specifies the following synchronous transmission:

- a) twisted-pair wire medium, 31,25 kbit/s, voltage mode (parallel coupling) with the options:
 - power via the bus conductors: not intrinsically safe;
 - power via the bus conductors: intrinsically safe;

and the following asynchronous transmission variants:

- b) twisted-pair wire medium, up to 12 Mbit/s, ANSI TIA/EIA-485-A;
- c) optical fiber medium, up to 12 Mbit/s, with type A4a of IEC 60793-2-40 and type A3c of IEC 60793-2-30.

0.4.4 Type 4: Wire medium

Type 4 specifies wire media with the following characteristics:

- RS-485 wire medium up to 76,8 kbit/s;

0.4.5 Type 8: Twisted-pair wire and optical media

The physical layer also allows transmitting data units that have been received through a medium access by the transmission medium directly through another medium access and its transmission protocol to another device.

Type 8 specifies the following variants:

- twisted-pair wire medium, up to 16 Mbit/s;
- optical fiber medium, up to 16 Mbit/s.

The general characteristics of these transmission media are as follows:

- full-duplex transmission;
- non-return-to-zero (NRZ) coding.

The wire media type provides the following options:

- no power supply via the bus cable, not intrinsically safe;
- power supply via the bus cable and on additional conductors, not intrinsically safe.

0.4.6 Type 12: Wire medium

Type 12 specifies wire media with the following characteristics:

- LVDS wire medium up 100 Mbit/s.

0.4.7 Type 16: optical media

Type 16 specifies a synchronous transmission using optical fiber medium, at 2 Mbit/s, 4 Mbit/s, 8 Mbit/s and 16 Mbit/s.

0.4.8 Type 18: Media

0.4.8.1 Type 18: Basic media

The Type 18-PhL-B specifies a balanced transmission signal over a shielded 3-core twisted cable. Communication data rates as high as 10 Mbit/s and transmission distances as great as 1,2 km are specified.

0.4.8.2 Type 18: Powered media

The Type 18-PhL-P specifies a balanced transmission signal over a 4-core unshielded cable in both flat and round configurations with conductors specified for communications signal and network-embedded power distribution. Communication data rates as high as 2,5 Mbit/s and transmission distances as great as 500 m are specified.

0.4.9 Type 20: Media

Type 20 uses binary phase continuous Frequency Shift Keying (FSK). A relatively high frequency current is superimposed on a low-frequency analog current, which is usually in 4 mA to 20 mA range. The digital signal and analog signal share the same medium, but differ in frequency contents. The communicating devices signal with either current or voltage, and all signaling appear as voltage when sensed across low impedance. Thus digital signaling is an extension of conventional analog signaling.

The physical layer commonly uses twisted pair copper cable as its medium and provides solely digital or simultaneous digital and analog communication to distances of at least 1 500 m (ca. 5 000 feet). Maximum communication distances vary depending on network construction and environmental conditions.

0.4.10 Type 24: Media

Type 24 specifies twisted-pair wire medium at 10 Mbit/s. The general characteristics of this transmission medium are as follows;

- ANSI TIA/EIA-485-A bus interface with galvanic isolation using transformer;
- half-duplex transmission;
- Manchester coding.

0.5 Patent declaration

The International Electrotechnical Commission (IEC) draws attention to the fact that it is claimed that compliance with this document may involve the use of a patent concerning Type 2 given in Subclauses 5.3, 9.4, 10.4, Clauses 18 through 20, Annex F through Annex H, as follows:

US 5,396,197 Network Node TAP

This patent is held by its inventor under license to ODVA, Inc.

IEC takes no position concerning the evidence, validity and scope of this patent right.

ODVA and the holder of this patent right have assured the IEC that ODVA is willing to negotiate licences either free of charge or under reasonable and non-discriminatory terms and conditions with applicants throughout the world. In this respect, the statement of ODVA and the holder of this patent right is registered with IEC. Information may be obtained from:

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Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights other than those identified above. IEC shall not be held responsible for identifying any or all such patent rights.

ISO (www.iso.org/patents) and IEC (<http://patents.iec.ch>) maintain on-line data bases of patents relevant to their standards. Users are encouraged to consult the data bases for the most up to date information concerning patents.

INDUSTRIAL COMMUNICATION NETWORKS – FIELDBUS SPECIFICATIONS –

Part 2: Physical layer specification and service definition

1 Scope

This part of IEC 61158 specifies the requirements for fieldbus component parts. It also specifies the media and network configuration requirements necessary to ensure agreed levels of

- a) data integrity before data-link layer error checking;
- b) interoperability between devices at the physical layer.

The fieldbus physical layer conforms to layer 1 of the OSI 7-layer model as defined by ISO 7498 with the exception that, for some types, frame delimiters are in the physical layer while for other types they are in the data-link layer.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.”

NOTE All parts of the IEC 61158 series, as well as IEC 61784-1 and IEC 61784-2 are maintained simultaneously. Cross-references to these documents within the text therefore refer to the editions as dated in this list of normative references.

IEC 60050 (all parts), *International Electrotechnical Vocabulary* (available at <http://www.electropedia.org>)

IEC 60079-11, *Explosive atmospheres – Part 11: Equipment protection by intrinsic safety “i”*

IEC 60079-14:2007, *Explosive atmospheres – Part 14: Electrical installations design, selection and erection*

IEC 60079-25, *Explosive atmospheres – Part 25: Intrinsically safe electrical systems*

IEC 60169-17, *Radio-frequency connectors – Part 17: R.F. coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with screw coupling – Characteristic impedance 50 ohms (Type TNC)*

IEC 60189-1:2007, *Low-frequency cables and wires with PVC insulation and PVC sheath – Part 1: General test and measuring methods*

IEC 60255-22-1:1988¹, *Electrical relays – Part 22-1: Electrical disturbance tests for measuring relays and protection equipment – Section 1: 1 MHz burst disturbance tests*

IEC 60364-4-41, *Low-voltage electrical installations – Part 4-41: Protection for safety – Protection against electric shock*

¹ This publication was withdrawn.

IEC 60364-5-54, *Low voltage electrical installations – Part 5-54: Selection and erection of electrical equipment – Earthing arrangements and protective conductors*

IEC 60529, *Degrees of protection provided by enclosures (IP Code)*

IEC 60603-7-4, *Connectors for electronic equipment – Part 7-4: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 250 MHz*

IEC 60754-2, *Test on gases evolved during combustion of materials from cables – Part 2: Determination of acidity (by pH measurement) and conductivity*

IEC 60793 (all parts), *Optical fibres*

IEC 60793-2-30:2012, *Optical fibres – Part 2-30: Product specifications – Sectional specification for category A3 multimode fibres*

IEC 60793-2-40:2009, *Optical fibres – Part 2-40: Product specifications – Sectional specification for category A4 multimode fibres*

IEC 60794-1-2:2003², *Optical fibre cables – Part 1-2: Generic specification – Basic optical cable test procedures*

IEC 60807-3, *Rectangular connectors for frequencies below 3 MHz – Part 3: Detail specification for a range of connectors with trapezoidal shaped metal shells and round contacts – Removable crimp contact types with closed crimp barrels, rear insertion/rear extraction*

IEC 60811-403, *Electric and optical fibre cables – Test methods for non-metallic materials – Part 403: Miscellaneous tests – Ozone resistance test on cross-linked compounds*

IEC 60811-404:2012, *Electric and optical fibre cables – Test methods for non-metallic materials – Part 404: Miscellaneous tests – Mineral oil immersion tests for sheaths*

IEC 61000-4-2, *Electromagnetic compatibility (EMC) – Part 4-2: Testing and measurement techniques — Electrostatic discharge immunity test* (Basic EMC Publication)

IEC 61000-4-3, *Electromagnetic compatibility (EMC) – Part 4-3: Testing and measurement techniques — Radiated, radio-frequency, electromagnetic field immunity test* (Basic EMC Publication)

IEC 61000-4-4, *Electromagnetic compatibility (EMC) – Part 4-4: Testing and measurement techniques — Electrical fast transient/burst immunity test* (Basic EMC Publication)

IEC 61131-2:2007, *Programmable controllers – Part 2: Equipment requirements and tests*

IEC 61156-1:2007, *Multicore and symmetrical pair/quad cables for digital communications – Part 1: Generic specification*

IEC 61158-3-20:2014, *Industrial communication networks – Fieldbus specifications – Part 3-20: Data-link layer service definition – Type 20 elements*

IEC 61158-4-2:2014, *Industrial communication networks – Fieldbus specifications – Part 4-2: Data-link protocol specification – Type 2 elements*

² There exists a new edition of IEC 60794-1-2 (2013). This will be considered in the next edition of IEC 61158-2.

IEC 61158-4-3:2014, *Industrial communication networks – Fieldbus specifications – Part 4-3: Data-link protocol specification – Type 3 elements*

IEC 61169-8:2007, *Radio-frequency connectors – Part 8: Sectional specification – RF coaxial connectors with inner diameter of outer conductor 6,5 mm (0,256 in) with bayonet lock – Characteristic impedance 50 Ω (type BNC)*

IEC 61210:2010, *Connecting devices – Flat quick-connect terminations for electrical copper conductors – Safety requirements*

IEC 61754-2, *Fibre optic connector interfaces – Part 2: Type BFOC/2,5 connector family*

IEC 61754-13, *Fibre optic connector interfaces – Part 13: Type FC-PC connector*

IEC 61754-22, *Fibre optic connector interfaces – Part 22: Type F-SMA connector family*

ISO/IEC 7498 (all parts), *Information technology – Open Systems Interconnection – Basic Reference Model*

ISO/IEC 7498-1:1994, *Information technology – Open Systems Interconnection – Basic Reference Model: The Basic Model*

ISO/IEC 8482, *Information technology – Telecommunications and information exchange between systems – Twisted pair multipoint interconnections*

ISO/IEC 8802-3, *Information technology – Telecommunications and information exchange between systems – Local and metropolitan area networks – Specific requirements – Part 3: Carrier sense multiple access with collision detection (CSMA/CD) access method and physical layer specifications*

ISO 9314-1, *Information processing systems – Fibre Distributed Data Interface (FDDI) Part 1: Token Ring Physical Layer Protocol (PHY)*

ISO/IEC 10731:1994, *Information technology – Open Systems Interconnection – Basic Reference Model – Conventions for the definition of OSI services*

ISO 4892-1, *Plastics – Methods of exposure to laboratory light sources – Part 1: General guidance*

ANSI TIA/EIA-422-B, *Electrical Characteristics of Balanced Voltage Digital Interface Circuits*

ANSI TIA/EIA-485-A, *Electrical Characteristics of Generators and Receivers for Use in Balanced Digital Multipoint Systems*

ANSI TIA/EIA-644-A, *Electrical Characteristics of Low Voltage Differential Signaling (LVDS) Interface Circuits*